

## N-Channel Super Junction Power MOSFET III

### **General Description**

The series of devices use advanced trench gate super junction technology and design to provide excellent RDS(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

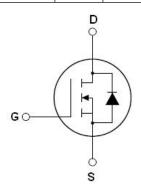
#### **Features**

- Optimized body diode reverse recovery performance
- ●Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

### **Application**

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

V <sub>DS min@Tjmax</sub>	710	٧
R <sub>DS(ON)TYP</sub>	62	mΩ
ID	45	Α
Qg	65	nC

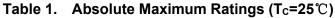


Schematic diagram

♦ Intrinsic fast-recovery body diode

### **Package Marking And Ordering Information**

Device	Device Package	Marking
NCE65TF078T	TO-247	NCE65TF078T





TO-247

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGS=0V)	V <sub>DS</sub>	650	V
Gate-Source Voltage (VDS=0V) AC (f>1 Hz)	V <sub>G</sub> s	±30	V
Continuous Drain Current at Tc=25°C	I <sub>D (DC)</sub>	45	А
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	28.3	А
Pulsed drain current (Note 1)	I <sub>DM (pluse)</sub>	135	А
Maximum Power Dissipation(Tc=25°C)	P <sub>D</sub>	400	W
Derate above 25°C		3.2	w/°C
Single pulse avalanche energy (Note 2)	Eas	907	mJ
Avalanche current <sup>(Note 1)</sup>	I <sub>AR</sub>	11	А
Repetitive Avalanche energy ,t <sub>AR</sub> limited by T <sub>jmax</sub> (Note 1)	E <sub>AR</sub>	0.9	mJ
Drain Source voltage slope, V <sub>DS</sub> ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, V <sub>DS</sub> ≤480 V,I <sub>SD</sub> <i<sub>D</i<sub>	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55+150	°C

<sup>\*</sup> limited by maximum junction temperature



**Table 2. Thermal Characteristic** 

Parameter	Symbol	Value	Unit
Thermal Resistance,Junction-to-Case(Maximum)	$R_{thJC}$	0.31	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	62	°C /W

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =500μA 650				V
Zero Gate Voltage Drain Current(Tc=25℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			10	μΑ
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			100	μΑ
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA	2.5	3.5	4.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =23A		62	78	mΩ
Dynamic Characteristics						
Input Capacitance	Clss	\/ -F0\/\/ -0\/		4000	4400	pF
Output Capacitance	Coss	$V_{DS}$ =50V, $V_{GS}$ =0V, F=1.0MHz		240		pF
Reverse Transfer Capacitance	Crss	F-1.0IVID2		1.1		pF
Total Gate Charge	Qg			65	75	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =480V,I <sub>D</sub> =23A,		24		nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =10V		15		nC
Gate plateau voltage	Vgp			6		V
Intrinsic gate resistance	R <sub>G</sub>	f = 1 MHz open drain		10.5		Ω
Switching times					•	
Turn-on Delay Time	t <sub>d(on)</sub>			16		nS
Turn-on Rise Time	t <sub>r</sub>	V <sub>DD</sub> =380V,I <sub>D</sub> =23A,		13		nS
Turn-Off Delay Time	t <sub>d(off)</sub>	R <sub>G</sub> =1.7Ω,V <sub>GS</sub> =10V		71		nS
Turn-Off Fall Time	t <sub>f</sub>			13		nS
Source- Drain Diode Characteristics					•	
Source-drain current(Body Diode)	I <sub>SD</sub>	T =25°C			45	Α
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>	T <sub>C</sub> =25°C			135	Α
Forward On Voltage	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =45A,V <sub>GS</sub> =0V		0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	Ti-25°C I -22A 4:/4t-422		180		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I <sub>F</sub> =23A,di/dt=100 A/µs		1.6		uC
Peak Reverse Recovery Current	I <sub>rrm</sub>	Ανμο		18		Α

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25 $^{\circ}$ C,VDD=50V,VG=10V, R<sub>G</sub>=25 $\Omega$ 

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### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

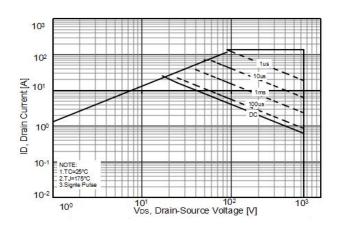


Figure 2. Capacitance

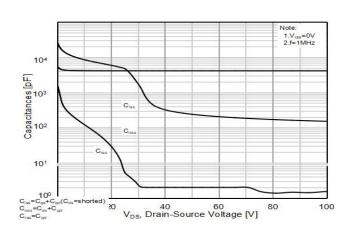


Figure 3. Source-Drain Diode Forward Voltage

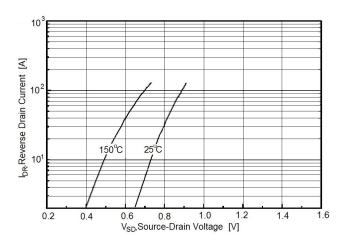


Figure 4. Output characteristics

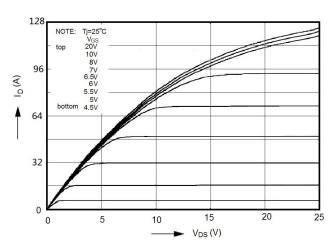


Figure 5. Transfer characteristics

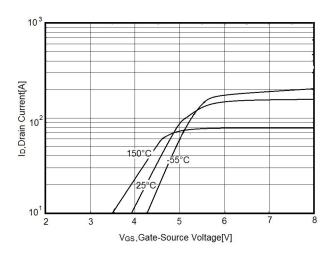


Figure 6. Static drain-source on resistance

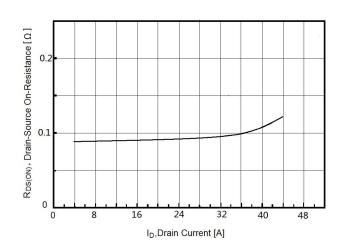




Figure 7. R<sub>DS(ON)</sub> vs Junction Temperature

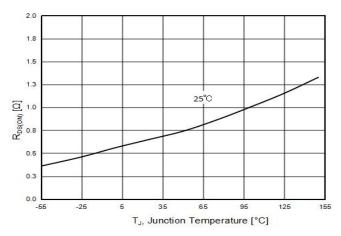


Figure 9. Maximum ID vs Junction Temperature

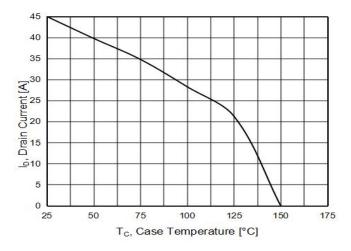


Figure8. BV<sub>DSS</sub> vs Junction Temperature

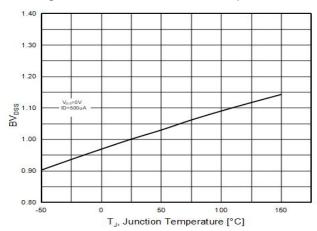
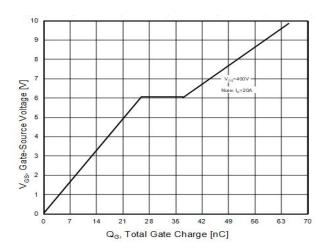


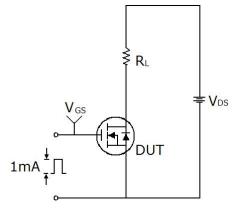
Figure 10. Gate charge waveforms

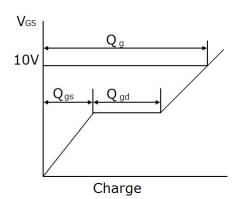




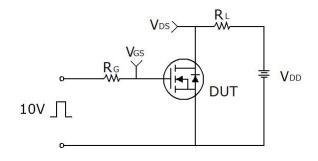
# **Test circuit**

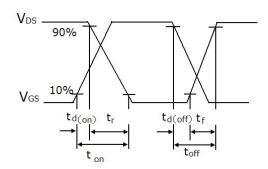
### 1) Gate charge test circuit & Waveform



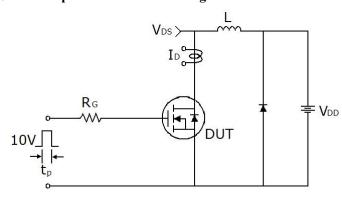


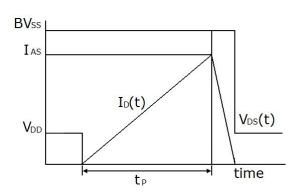
### 2) Switch Time Test Circuit:





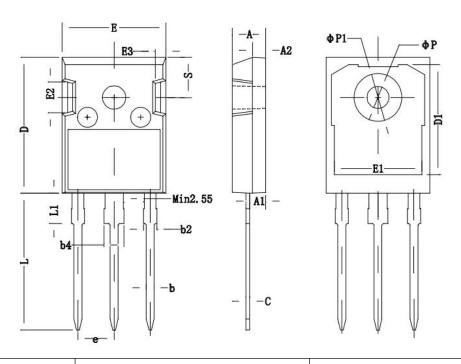
### 3) Unclamped Inductive Switching Test Circuit & Waveforms







# **TO-247 Package Information**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.80	5.20	0.19	0.20
A1	2.21	2.59	0.09	0.10
A2	1.85	2.15	0.07	0.08
b	1.11	1.36	0.04	0.05
b2	1.91	2.21	0.08	0.09
b4	2.91	3.21	0.11	0.13
С	0.51	0.75	0.02	0.03
D	20.80	21.30	0.82	0.84
D1	16.25	16.85	0.64	0.66
E	15.50	16.10	0.61	0.63
E1	13.00	13.60	0.51	0.54
E2	4.80	5.20	0.19	0.20
E3	2.30	2.70	0.09	0.11
е	5.44 B	5.44 BSC		I BSC
L	19.82	20.22	0.78	0.80
L1	-	4.30	-	0.17
ФР	3.40	3.80	0.13	0.15
ФР1	-	7.30	-	0.29
S	6.15BSC		0.24 BSC	



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